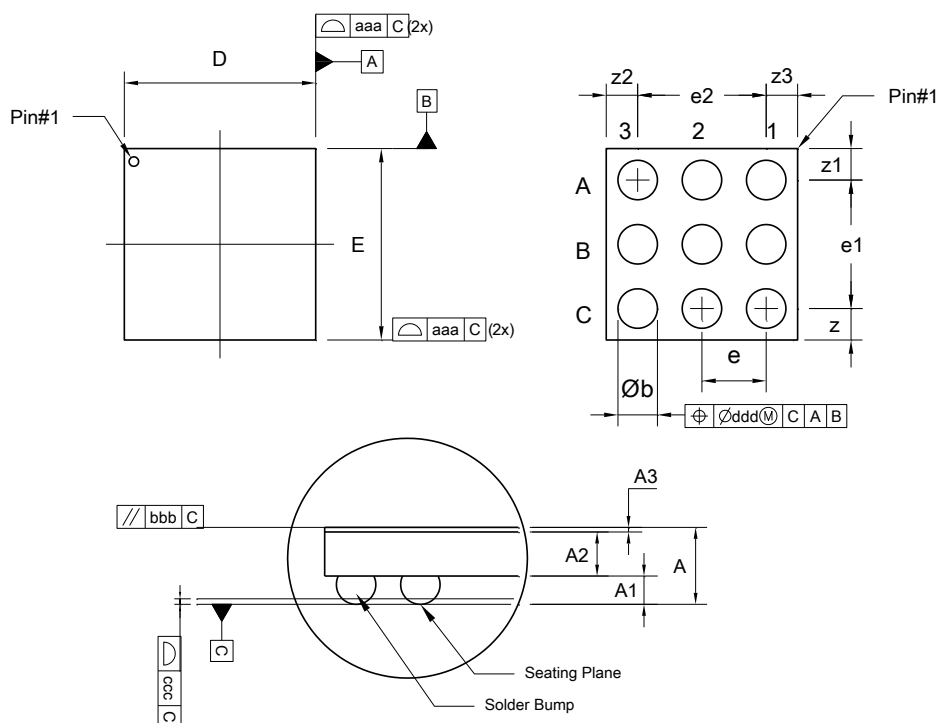


Package Outline Dimensions

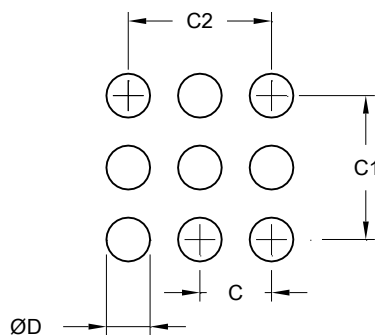
X1-WLB1010-9 (Type A1)



X1-WLB1010-9 (Type A1)			
Dim	Min	Max	Typ
A	0.3756	0.4624	0.4190
A1	0.1386	0.1694	0.1540
A2	0.2150	0.2650	0.2400
A3	0.0220	0.0280	0.0250
b	0.1828	0.2473	0.2150
D	1.0150	1.0700	1.0425
E	1.0150	1.0700	1.0425
e	--	--	0.3500
e1	--	--	0.7000
e2	--	--	0.7000
z	--	--	0.1713
z1	--	--	0.1713
z2	--	--	0.1713
z3	--	--	0.1713
aaa	--	--	0.0275
bbb	--	--	0.0600
ccc	--	--	0.0300
ddd	--	--	0.1500
All Dimensions in mm			

Suggested Pad Layout

X1-WLB1010-9 (Type A1)



Dimensions	Value (in mm)
C	0.3500
C1	0.7000
C2	0.7000
D	0.2150

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.